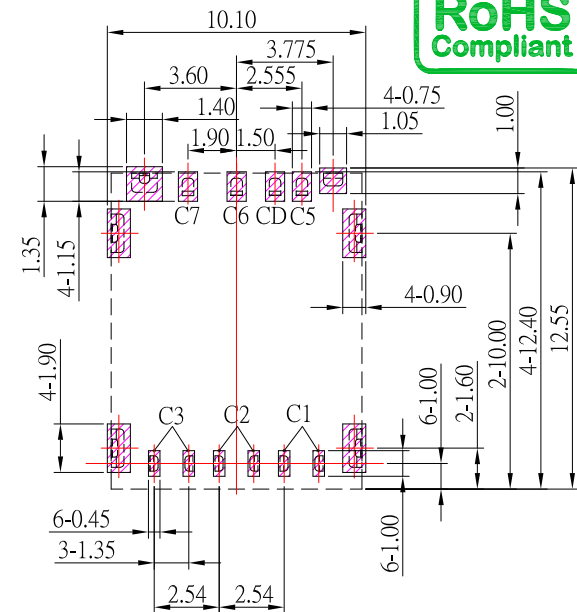
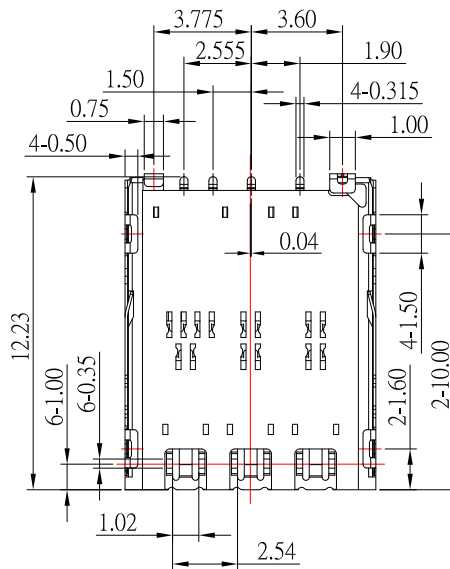
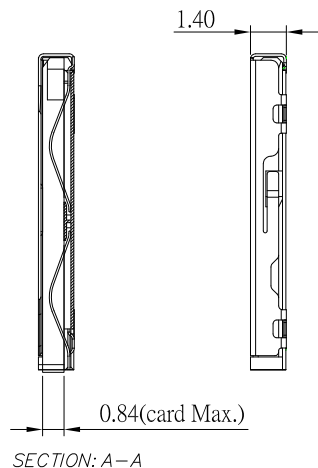
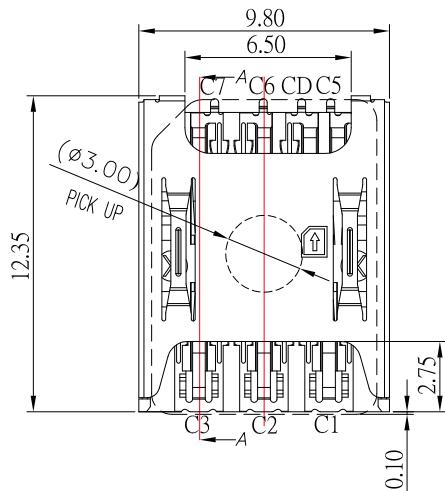




/// SMT SOLDER AREA.
□ CONNECTOR AREA

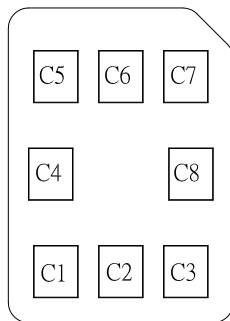
P.C.B LAYOUT MOUNTING PATTERN

SW Circuit Description for Connector:

CARD INSERTION STATE	DETECT SWITCH CIRCUIT STATE	SCHEMATIC
UNMATED	OPENED	DETECT PIN [C2] — [C5]
MATED	CLOSED	DETECT PIN [C2] — [C5]

Nano SIM Circuit Description:

PIN No.	FUNCTION
C1	VCC
C2	RST
C3	CLK
C4	RESERVED
C5	GND
C6	VPP
C7	I/O
C8	RESERVED



MATERIALS:

1. HOUSING : LCP
2. CONTACT : PHOSPHOR BRONZE
3. SHELL : SUS

Finish:

1. Finish: CONTACT: PLATED GOLD IN MATING AREA ;
GOLD PLATED ON SOLDER BALLS ;
NICKEL UNDER PLATED OVERALL
2. SHELL: NICKEL UNDER PLATED SURFACE LAYER

SPECIFICATION:

1. CURRENT RATING : 0.5A MAX.
2. VOLTAGE RATING : 5.0V AC / DC
3. INSULATION RESISTANCE : 1000MΩ MIN.
4. CONTACT RESISTANCE : 100mΩ MAX.
5. OPERATING TEMPERATURE RANGE : -40°C TO +85°C.
6. STORAGE TEMPERATURE RANGE : -40°C TO +85°C.



广东科斯达电子科技有限公司
GUANG DONG KE SI DA ELECTRONIC TECHNOLOGY CO., LTD.

TOLERANCE UNLESS OTHERWISE STATED :
Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3

3RD.
ANGEL'S



UNITS

MM

DRAWN BY: Jack Lu
CHECKED BY: Jacky Chen
APPROVED BY: Tony Kao
DATE: 03/23/23

MAT'L	TITLE	CONNECTOR
FINISH	MODLE	Nano SIM CARD PUSH PUSH 1.40H
SCALE	DWG NO.	NSIM-111308-S267
SHEET NO.	PART NO.	NSIM-111308-S267

ITEM NO.	DESCRIPTION	DRAWN	DATE
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